

In The Claims:

1. (Cancelled).
2. (Cancelled).
3. (Currently Amended) ~~The apparatus of claim 1 further comprising~~
A hermetic seal for an electronic circuit die comprising:
an inorganic layer for preventing moisture from reaching the electronic
circuit die;
an organic layer outside the inorganic layer for protecting the inorganic
layer; and
a plastic package.
4. (Original) The apparatus of claim 3 wherein the inorganic layer is outside the plastic package.
5. (Original) The apparatus of claim 4 wherein the inorganic layer is inside the plastic package.
6. (Currently Amended) ~~The apparatus of claim 1 further comprising:~~
A hermetic seal for an electronic circuit die comprising:
an inorganic layer for preventing moisture from reaching the electronic
circuit die;
an organic layer outside the inorganic layer for protecting the inorganic
layer;
a lead; and
a wire; wherein the inorganic layer contacts the lead.

7. (Cancelled).

8. (Currently Amended) ~~The apparatus of claim 1 wherein~~

A hermetic seal for an electronic circuit die comprising:

an inorganic layer for preventing moisture from reaching the electronic circuit die; and

an organic layer outside the inorganic layer for protecting the inorganic layer, the organic layer ~~comprises~~ comprising a material consisting of para-xylyene, hybrid solgel, and polymeric materials.

9. (Withdrawn) A method of making a hermetic seal comprising:
providing an inorganic layer for protecting from moisture; and
providing an organic layer for protecting the inorganic layer.

10. (Withdrawn) The method of claim 9 further comprising:
providing a lead, wherein the lead contacts the inorganic material.

11. (Withdrawn) The method of claim 9 further comprising providing a plastic package.

12. (Withdrawn) The method of claim 11, wherein the plastic package contacts the inorganic layer.

13. (Withdrawn) The method of claim 11, wherein the plastic package contacts the organic layer.

14. (Cancelled).

15. (Currently Amended) ~~The hermetically sealed device of claim 14 further comprising:~~

A hermetically sealed device comprising:

an electronic circuit die;
an inorganic layer outside the electronic circuit die;
an organic layer outside the inorganic material;
a wire; and
a lead; wherein the inorganic layer contacts the lead.

16. (Cancelled).

17. (Currently Amended) ~~The hermetically sealed device of claim 14 wherein~~
A hermetically sealed device comprising:

an electronic circuit die;
an inorganic layer outside the electronic circuit die; and
an organic layer outside the inorganic material, the organic layer ~~comprises~~
comprising a material consisting of para-xylyene, hybrid solgel, and
polymeric materials.

18. (Currently Amended) ~~The hermetically sealed device of claim 14 further comprising:~~

A hermetically sealed device comprising:

an electronic circuit die;
an inorganic layer outside the electronic circuit die;
an organic layer outside the inorganic material;
a wire;
a lead; and
a plastic package.


19. (Original) The hermetically sealed device of claim 18 wherein the plastic package contacts the inorganic layer.

20. (Original) The hermetically sealed device of claim 18 wherein the plastic package contacts the organic layer.

21. (Cancelled).

Respectfully submitted,

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